Earth Leakage Detector

KA2803

Description

The KA2803 is designed for use in earth leakage circuit interrupters, for operation directly off the AC line in breakers. The input of the differential amplifier is connected to the secondary coil of Zero Current Transformer (ZCT). The amplified output of differential amplifier is integrated at external capacitor to gain adequate time delay. The level comparator generates a high level when earth leakage current is greater than the fixed level.

Features

- Low Power Consumption: 5 mW, 100 V/200 V
- Built-in Voltage Regulator
- High-gain Differential Amplifier
- 0.4 mA Output Current Pulse to Trigger SCRs
- Low External Part Count
- SOP Package, High Packing Density
- High Noise Immunity, Large Surge Margin
- Super Temperature Characteristic of Input Sensitivity
- Wide Operating Temperature Range:
 T_A=-25°C to +80°C for KA2803B and KA2803BDTF
 T_A = -25°C to +100°C for KA2803CDTF
- Operation from 12 V to 20 V Input

Functions

- Differential Amplifier
- Level Comparator
- Latch Circuit



ON Semiconductor®

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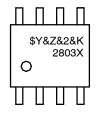


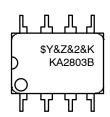


SOIC8 CASE 751EB

PDIP-8 CASE 626-05

MARKING DIAGRAM





\$Y &Z = ON Semiconductor Logo= Assembly Plant Code

&2

= Data Code (Year & Week)

&K KA2803B or 2803X

LotSpecific Device Code

X = B or C

ORDERING INFORMATION

See detailed ordering and shipping information on page 10 of this data sheet.

BLOCK DIAGRAM

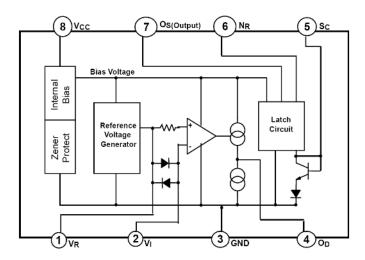


Figure 1. Block Diagram

PIN CONFIGURATION

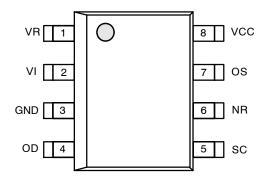
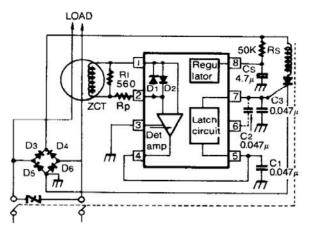


Figure 2. Pin Assignment

PIN DESCRIPTION

Pin No.	Name	Description			
1	VR	Non inverting input for current sensing amplifier			
2	VI	nverting Input for current sensing amplifier			
3	GND	Ground			
4	OD	Output of current sensing amplifier			
5	SC	nput of latch circuit			
6	NR	Noise absorption			
7	os	Gate drive for external SCR			
8	VCC	Power supply input for KA2803 circuitry			

APPLICATION CIRCUITS



LOAD

50K Rs

8 Cs π 7 C3

Ccs π 7 C3

Ccs π 6 C1

Det Circuit 6 C1

0.047μ

1 0.047μ

Figure 3. Full-wave Application Circuit

Figure 4. Half-wave Application Circuit

APPLICATION INFORMATION

(Refer to full-wave application circuit in Figure 3)

Figure 3 shows the KA2803 connected in a typical leakage current detector system. The power is applied to the V_{CC} terminal (Pin 8) directly from the power line. The resistor R_S and capacitor C_S are chosen so that Pin 8 voltage is at least 12 V. The value of C_S is recommended above 1 μF .

If the leakage current is at the load, it is detected by the Zero Current Transformer (ZCT). The output voltage signal of ZCT is amplified by the differential amplifier of the KA2803 internal circuit and appears as a half-cycle sine wave signal referred to input signal at the output of the amplifier. The amplifier closed-loop gain is fixed about 1000 times with internal feedback resistor to compensate for Zero Current Transformer (ZCT) variations. The resistor R_L should be selected so that the breaker satisfies the required sensing current. The protection resistor R_P is not usually used when high current is injected at the breaker; this resistor should be used to protect the earth leakage detector IC

(KA2803). The range of R_P is from several hundred Ω to several $k\Omega$.

Capacitor C_1 is for the noise canceller and a standard value of C_1 is 0.047 μF . Capacitor C_2 is also a noise canceller capacitance, but it is not usually used.

When high noise is present, a 0.047 μF capacitor may be connected between Pins 6 and 7. The amplified signal finally appears at the Pin 7 with pulse signal through the internal latch circuit of the KA2803. This signal drives the gate of the external SCR, which energizes the trip coil, which opens the circuit breaker. The trip time of the breaker is determined by capacitor C_3 and the mechanism breaker. This capacitor should be selected under 1 μF to satisfy the required trip time. The full-wave bridge supplies power to the KA2803 during both the positive and negative half cycles of the line voltage. This allows the hot and neutral lines to be interchanged.

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Min.	Max.	Unit
Vcc	Supply Voltage		20	V
Icc	Supply Current		8	mA
P _D	Power Dissipation		300	mW
TL	Lead Temperature, Soldering 10 Seconds		260	°C
T _A	Operation Temperature Range for KA2803B and KA2803BDTF	-25	80	°C
	Operation Temperature Range for KA2803CDTF	-25	+100	°C
Тѕтс	Storage Temperature Range	-65	+150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS (For KA2803B and KA2803BDTF, $T_A = -25^{\circ}\text{C}$ to 80°C unless otherwise noted. For KA2803CDTF, $T_A = -25^{\circ}\text{C}$ to +100°C unless otherwise noted.)

Symbol	Parameter	Conditions		Test Circuit	Min.	Тур.	Max.	Units
Icc	Supply Current 1	V _{CC} = 12V,	T _A = -25°C	Figure 5			580 530	μΑ
		$V_R = OPEN,$ $V_I = 2 V$	T _A = +25°C		300	400		
			T _A = +100°C	1			480	
V _T	Trip Voltage	$V_{CC} = 16 \text{ V},$ $V_{R} = 2 \text{ V} \sim 2.02 \text{ V},$ $V_{I} = 2 \text{ V}$	T _A = +25°C	Figure 6	14	16	18	mV (rms)
IO(D)	Differential Amplifier Current Current 1	$V_{CC} = 16 \text{ V},$ $V_{R} \sim V_{I} = 30 \text{ mV},$ $V_{OD} = 1.2 \text{ V}$	T _A = +25°C	Figure 8	-12	-20	-30	μА
	Differential Amplifier Current Current 2	$V_{CC} = 16 \text{ V},$ $V_{OD} = 0.8 \text{ V}, V_{R},$ $V_{I} \text{ Short} = V_{P}$	T _A = +25°C	Figure 9	17	27	37	
I _O	Output Current	V _{SC} = 1.4 V, V _{OS} = 0.8 V, V _{CC} = 16.0 V	T _A = -25°C	Figure 10	200	400	800	μΑ
			T _A = +25°C		200	400	800	
			T _A = +100°C		100	300	600	
Vscon	Latch-On Voltage	V _{CC} = 16 V		Figure 11	0.7	1.0	1.4	V
Iscon	Latch Input Current	V _{CC} = 16 V		Figure 12	-13	-7	-1	μΑ
Iosl	Output Low Current	V _{CC} = 12 V, V _{OSL} = 0.2 V		Figure 13	200	800	1400	μΑ
VIDC	Differential Input Clamp Voltage	V _{CC} = 16 V, I _{IDC} = 100 mA		Figure 14	0.4	1.2	2.0	V
VsM	Maximum Current Voltage	I _{SM} = 7 mA		Figure 15	20	24	28	V
ls2	Supply Current 2	V _{CC} = 12.0 V, V _{OSL} = 0.6 V		Figure 16	200	400	900	μΑ
Vsoff	Latch-Off Supply Voltage	V _{OS} = 12.0 V		Figure 17	7	8	9	V
		V _{SC} = 1.8 V						
		I _{IDC} = 100.0 mA		1				
ton	Response Time	V _{CC} = 16 V, V _R -V _I = 0.3 V, 1 V < V _X < 5 V		Figure 18	2	3	4	ms

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

^{1.} Guaranteed by design, not tested in production.

TEST CIRCUITS

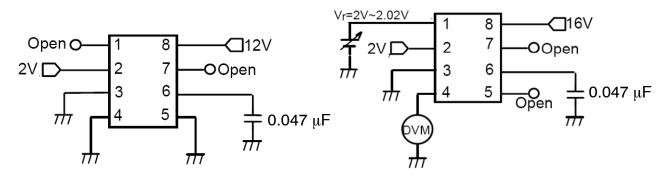


Figure 5. Supply Current 1

Figure 6. Trip Voltage

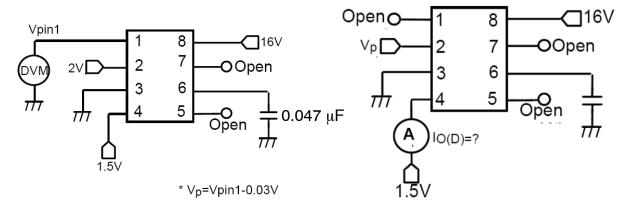


Figure 7. V_{PN1} for V_P Measurement

Figure 8. Differential Amplifier Output Current 1

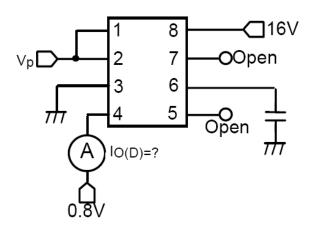


Figure 9. Differential Amplifier Output Current 2

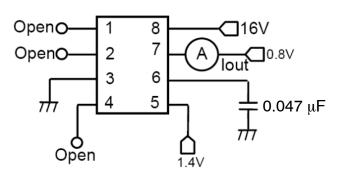


Figure 10. Output Current

TEST CIRCUITS (Continued)

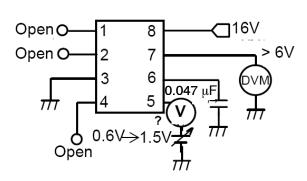


Figure 11. Latch-On Voltage

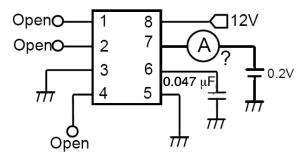


Figure 13. Output Low Current

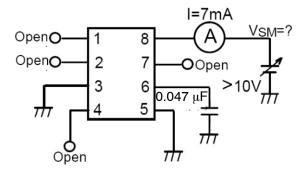


Figure 15. Maximum Current Voltage

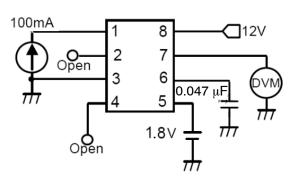


Figure 17. Latch-Off Supply Voltage

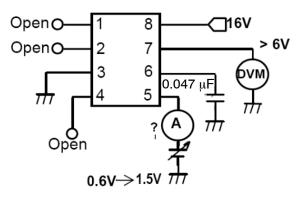


Figure 12. Latch Input Current

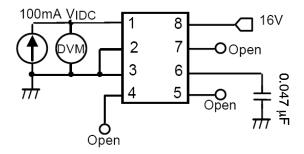


Figure 14. Differential Input Clamp Voltage

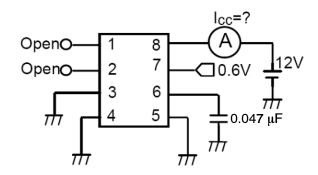


Figure 16. Supply Current 2

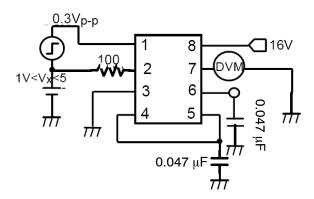


Figure 18. Response Time

TYPICAL PERFORMANCE CHARACTERISTICS

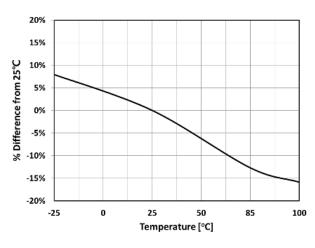


Figure 19. Supply Current

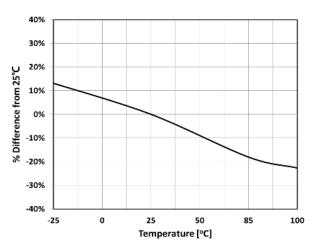


Figure 21. Differential Amplifier Output Current $(V_B, V_I = V_P, V_{OD} = 0.8 \text{ V})$

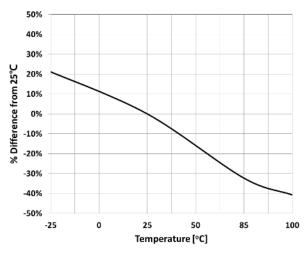


Figure 23. Output Low Current

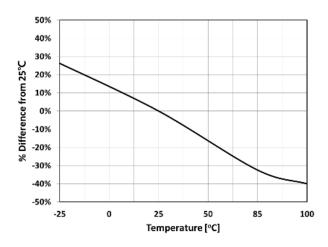


Figure 20. Differential Amplifier Output Current $(V_R - V_I = 30 \text{ mV}, V_{OD} = 1.2 \text{ V})$

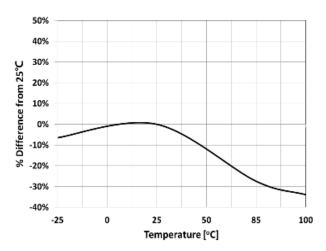


Figure 22. Output Current

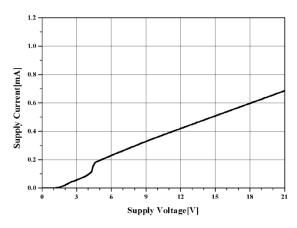


Figure 24. V_{CC} Voltage vs. Supply Current 1

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

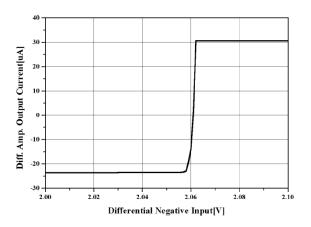


Figure 25. Differential Amplifier Output Current 1

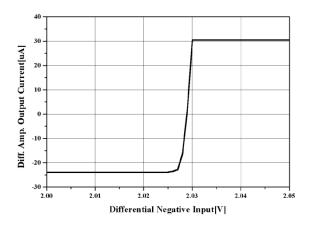


Figure 26. Differential Amplifier Output

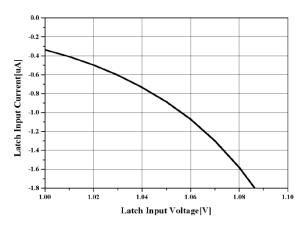


Figure 27. Latch Input Current

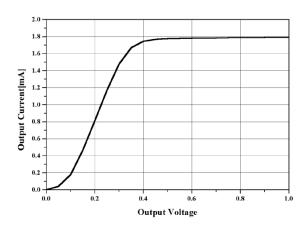


Figure 28. Output Low Current

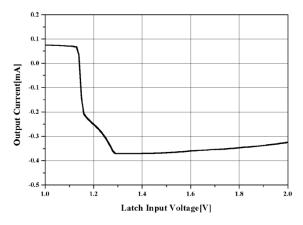


Figure 29. Output Current

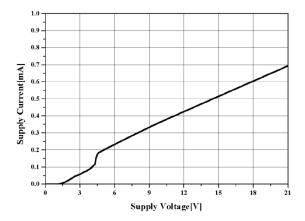


Figure 30. V_{CC} Voltage vs. Supply Current 2

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

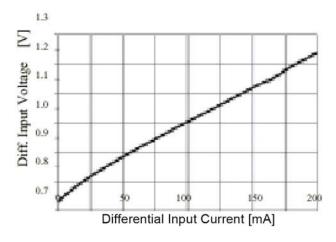


Figure 31. Differential Input Clamp Voltage

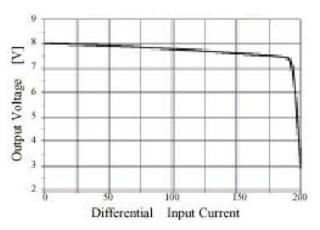


Figure 32. Latch-Off Supply Voltage

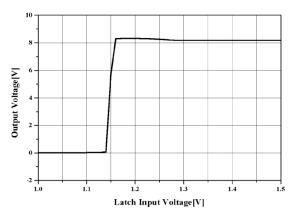


Figure 33. Latch-On Input Voltage

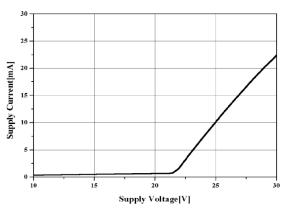


Figure 34. Maximum Supply

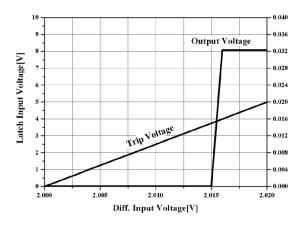


Figure 35. Trip and Output

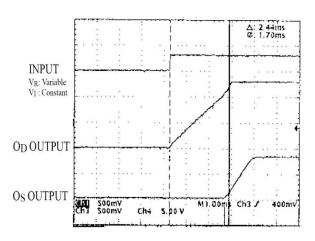


Figure 36. Output Response Time

ORDERING INFORMATION

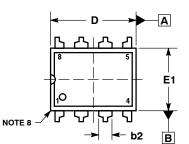
Part Number	Operating Temperature Range	Package	Shipping [†]
KA2803CDTF	−25 to +100°C	8-lead, Small Outline Package (SOP)	3,000 / Tape& Reel
KA2803B	−25 to 80°C	8-lead, Plastic Dual Inline Package (PDIP)	3,000 / Tube
KA2703BDTF	−25 to 80°C	8-lead, Small Outline Package (SOP)	3,000 / Tape& Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

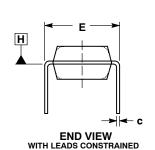


PDIP-8 CASE 626-05 ISSUE P

DATE 22 APR 2015



TOP VIEW



NOTE 5

e/2 NOTE 3 SEATING PLANE C D1 eВ 8X b **END VIEW** |⊕|0.010 M| C| A M| B M NOTE 6

STYLE 1: PIN 1. AC IN 2. DC + IN 3. DC - IN 4. AC IN

5. GROUND 6. OUTPUT

SIDE VIEW

7. AUXILIARY 8. V_{CC}

NOTES

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: INCHES.
 DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACK-
- AGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
 DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE NOT TO EXCEED 0.10 INCH.
- DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR
- 6. DIMENSION eB IS MEASURED AT THE LEAD TIPS WITH THE
- DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE LEADS, WHERE THE LEADS EXIT THE BODY.
- 8. PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE CORNERS).

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α		0.210		5.33	
A1	0.015		0.38		
A2	0.115	0.195	2.92	4.95	
b	0.014	0.022	0.35	0.56	
b2	0.060 TYP		1.52 TYP		
С	0.008	0.014	0.20	0.36	
D	0.355	0.400	9.02	10.16	
D1	0.005		0.13		
Е	0.300	0.325	7.62	8.26	
E1	0.240	0.280	6.10	7.11	
е	0.100 BSC		2.54	BSC	
eВ		0.430		10.92	
L	0.115	0.150	2.92	3.81	
M		10°		10°	

GENERIC MARKING DIAGRAM*



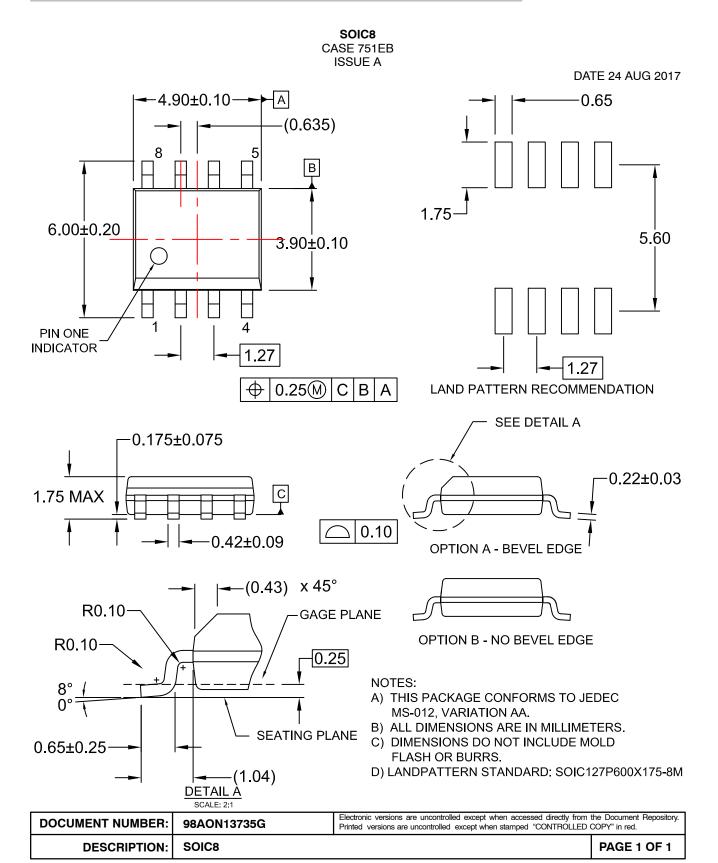
XXXX = Specific Device Code = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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